

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (canceled).
2. (canceled).
3. (currently amended): A printed wiring substrate comprising:
a core substrate having a front surface and a back surface; and
an electronic component embedded in said core substrate;
said printed wiring substrate characterized in that:
said electronic component has an electrode projecting from at least either an upper end or
a lower end thereof; and
said core substrate or a resin embedding the electronic component in the core substrate
contains an inorganic filler.
4. (currently amended): The printed wiring substrate as claimed in ~~claim 1~~ claim 13,
wherein the inorganic filler has a particle size not greater than one-half the height of said
electrode.
5. (currently amended): The printed wiring substrate as claimed in ~~claim 2~~ claim 14,
wherein the inorganic filler has a particle size not greater than one-half the height of said
electrode.

6. (original): The printed wiring substrate as claimed in claim 3, wherein the inorganic filler has a particle size not greater than one-half the height of said electrode.

7. (currently amended): The printed wiring substrate as claimed in ~~claim 1~~ claim 13, wherein the inorganic filler has a particle size not greater than 25 μm , and the electrode has a height of at least 50 μm .

8. (currently amended): The printed wiring substrate as claimed in ~~claim 2~~ claim 14, wherein the inorganic filler has a particle size not greater than 25 μm , and the electrode has a height of at least 50 μm .

9. (original): The printed wiring substrate as claimed in claim 3, wherein the inorganic filler has a particle size not greater than 25 μm , and the electrode has a height of at least 50 μm .

10. (original): The printed wiring substrate as claimed in claim 4, wherein the inorganic filler has a particle size not greater than 25 μm , and the electrode has a height of at least 50 μm .

11. (currently amended): A method for manufacturing a printed wiring substrate comprising a core substrate having a front surface and a back surface and an electronic component embedded via a resin in a through-hole extending through the core substrate between the front surface and back surface of the core substrate ~~or in a recess formed in the core substrate and extending from an interior of the core substrate to the front surface or the back surface~~, said method comprising the steps of:

inserting into the through-hole ~~or the recess~~ the electronic component having an electrode projecting from at least either an upper end or a lower end thereof;

embedding the electronic component in the through-hole ~~or the recess~~ by means of a resin containing an inorganic filler; and

polishing a surface of the resin so as to expose an end surface of the electrode.

12. (new): A method for manufacturing a printed wiring substrate comprising a core substrate having a front surface and a back surface and an electronic component embedded via a resin in a recess formed in the core substrate and extending from an interior of the core substrate to the front surface or the back surface, said method comprising the steps of:

inserting into the through-hole or the recess the electronic component having an electrode projecting from at least either an upper end or a lower end thereof;

embedding the electronic component in the recess by means of a resin containing an inorganic filler; and

polishing a surface of the resin so as to expose an end surface of the electrode.

13. (new): The printed wiring substrate as claimed in claim 3, wherein said electronic component is embedded in the core substrate via a resin in a through-hole extending through said core substrate between the front surface and the back surface of the core substrate, and the resin contains said inorganic filler.

14. (new): The printed wiring substrate as claimed in claim 3, wherein said electronic component is embedded in the core substrate via a resin in a recess formed in said core substrate and extending from an interior of said core substrate to the front surface or back surface of the core substrate, and the resin contains said inorganic filler.